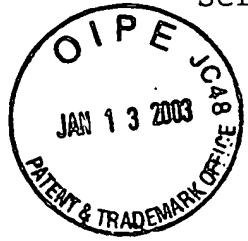


MEG00-001

Serial number 09/684,519



TO: COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)  
28 Davis Avenue  
Poughkeepsie, NY 12603

Date: December 15, 2002

REF: APPLICANT : Jin-Yuan Lee  
SERIAL NO. : 09/684,519  
ART UNIT : 2841  
FILING DATE : 10/10/00  
ATT'Y NO. : MEG01-001  
EXAMINER : Bui, Hung S.  
TITLE : A THERMALLY COMPLIANT PCB  
SUBSTRATE FOR THE APPLICATION  
OF CHIP SCALE PACKAGES.

RECEIVED  
JAN 15 2003  
TECHNOLOGY CENTER 2800

10

~17-03  
J.W.

#### AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

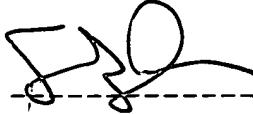
In response to an office action mailed on 11/04/02  
please consider the following amendments and remarks with  
respect to the above referenced application.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal service as First  
Class mail in an envelop addressed to the Commissioner of  
Patents and Trademarks, Washington, D.C. 20231, on

January 6, 2003

Stephen B. Ackerman (Reg. No 37,761)

  
Signature

1/6/03  
Date